### NE5532, NE5532A, SA5532, SA5532A DUAL LOW-NOISE OPERATIONAL AMPLIFIERS

SLOS075H - NOVEMBER 1979 - REVISED MAY 2004

- Equivalent Input Noise Voltage
  5 nV/√Hz Typ at 1 kHz
- Unity-Gain Bandwidth . . . 10 MHz Typ
- Common-Mode Rejection Ratio . . . 100 dB Typ
- High dc Voltage Gain . . . 100 V/mV Typ
- Peak-to-Peak Output Voltage Swing 32 V Typ With  $V_{CC\pm} = \pm 18 \text{ V}$  and  $R_L = 600 \Omega$
- High Slew Rate . . . 9 V/μs Typ
- Wide Supply-Voltage Range . . . ±3 V to ±20 V

#### 

### description/ordering information

The NE5532A, SA5532A, and SA5532A\_are high-performance operational amplifiers combining excellent dc and ac characteristics. They feature very low noise, high output-drive capability, high unity-gain and maximum-output-swing bandwidths, low distortion, high slew rate, input-protection diodes, and output short-circuit protection. These operational amplifiers are compensated internally for unity-gain operation. These devices have specified maximum limits for equivalent input noise voltage.

#### ORDERING INFORMATION

TA	PACKAG	GE†	ORDERABLE PART NUMBER	TOP-SIDE MARKING	
	PDIP – P	Tube of 50	NE5532P	NE5532P	
	PDIP – P Tube of 50		NE5532AP	NE5532AP	
		Tube of 75	NE5532D	NEEDO	
000 1- 7000	0010 0	Reel of 2500	NE5532DR	N5532	
0°C to 70°C	SOIC - D	Tube of 75	NE5532AD	NEEGOA	
		Reel of 2500	NE5532ADR	N5532A	
	000 00	D1 - ( 0000	NE5532PSR	N5532	
	SOP – PS	Reel of 2000	NE5532APSR	N5532A	
	DDID D	T. b (50	SA5532P	SA5532P	
	PDIP – P	Tube of 50	SA5532AP	SA5532AP	
-40°C to 85°C		Tube of 75	SA5532D	045500	
-40 C to 85°C	SOIC - D	Reel of 2500	SA5532DR	SA5532	
	3010 - 0	Tube of 75	SA5532AD	SA5532A	
		Reel of 2500	SA5532ADR	SASSSZA	

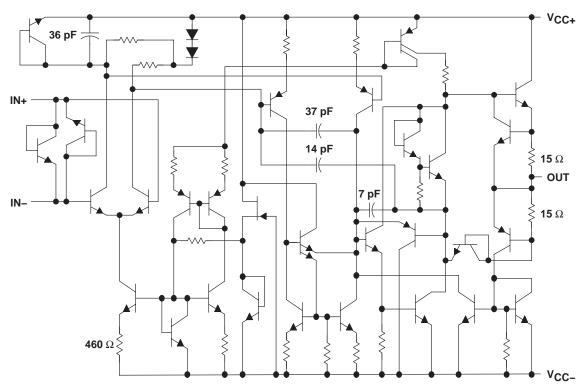
<sup>†</sup> Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



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#### schematic (each amplifier)



Component values shown are nominal.

### absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage (see Note 1): V <sub>CC+</sub>	22 V
V <sub>CC</sub>	22 V
Input voltage, either input (see Notes 1 and 2)	V <sub>CC±</sub>
Input current (see Note 3)	±10 mA
Duration of output short circuit (see Note 4)	Unlimited
Package thermal impedance, $\theta_{JA}$ (see Notes 5 and 6):	D package 97°C/W
	P package 85°C/W
	PS package 95°C/W
Operating virtual junction temperature, T <sub>J</sub>	
Storage temperature range, T <sub>stg</sub>	–65°C to 150°C

<sup>†</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. All voltage values, except differential voltages, are with respect to the midpoint between V<sub>CC+</sub> and V<sub>CC-</sub>.
  - 2. The magnitude of the input voltage must never exceed the magnitude of the supply voltage.
  - 3. Excessive input current will flow if a differential input voltage in excess of approximately 0.6 V is applied between the inputs, unless some limiting resistance is used.
  - 4. The output may be shorted to ground or either power supply. Temperature and/or supply voltages must be limited to ensure the maximum dissipation rating is not exceeded.
  - Maximum power dissipation is a function of T<sub>J</sub>(max), θ<sub>JA</sub>, and T<sub>A</sub>. The maximum allowable power dissipation at any allowable ambient temperature is P<sub>D</sub> = (T<sub>J</sub>(max) – T<sub>A</sub>)/θ<sub>JA</sub>. Operating at the absolute maximum T<sub>J</sub> of 150°C can affect reliability.
  - 6. The package thermal impedance is calculated in accordance with JESD 51-7.



## NE5532, NE5532A, SA5532, SA5532A DUAL LOW-NOISE OPERATIONAL AMPLIFIERS

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### recommended operating conditions

			MIN	MAX	UNIT
V <sub>CC+</sub>	Supply voltage		5	15	V
VCC-	Supply voltage		-5	-15	V
т.	Operating free cir temperature renge	NE5532, NE5532A	0 70		• °C
TA	Operating free-air temperature range	-40	85		

# electrical characteristics, $V_{CC\pm}$ = +15 V, $T_A$ = 25°C (unless otherwise noted)

PARAMETER		TEST CONDITIONS†				NE5532, NE5532A SA5532, SA5532A		
					MIN	TYP	MAX	
	land effect well-	., .	T <sub>A</sub> = 25°C			0.5	4	>/
VIO	Input offset voltage	VO = 0	T <sub>A</sub> = Full range‡				5	mV
		T <sub>A</sub> = 25°C			10	150		
liO	Input offset current	T <sub>A</sub> = Full range‡					200	nA
		T <sub>A</sub> = 25°C				200	800	
l <sub>IB</sub>	Input bias current	T <sub>A</sub> = Full range‡					1000	nA
VICR	Common-mode input-voltage range				±12	±13		V
	Maximum peak-to-peak		V <sub>CC±</sub> = ±15 V		24	26		
VOPP	output-voltage swing	R <sub>L</sub> ≥ 600 Ω	V <sub>CC±</sub> = ±18 V	30	32		V	
	Large-signal differential-voltage amplification	$R_1 \geq 600 \Omega$	$T_A = 25$ °C $T_A = \text{Full range}^{\ddagger}$		15	50		V/mV
		$V_0 = \pm 10 \text{ V}$			10			
$A_{VD}$		$R_1 \ge 2 k\Omega$	T <sub>A</sub> = 25°C	25	100			
		$V_{O} = \pm 10 \text{ V}$	T <sub>A</sub> = Full range‡	15				
A <sub>vd</sub>	Small-signal differential-voltage amplification	f = 10 kHz				2.2		V/mV
,		5	V <sub>O</sub> = ±10 V			140		
BOM	Maximum-output-swing bandwidth	$R_L = 600 \Omega$	$V_{CC\pm} = \pm 18 \text{ V},$	V <sub>O</sub> = ±14 V		100		kHz
B <sub>1</sub>	Unity-gain bandwidth	$R_L = 600 \Omega$ ,	C <sub>L</sub> = 100 pF			10		MHz
rį	Input resistance				30	300		kΩ
z <sub>o</sub>	Output impedance	$A_{VD} = 30 \text{ dB},$	$R_L = 600 \Omega$ ,	f = 10 kHz		0.3		Ω
CMRR	Common-mode rejection ratio	VIC = VICR min			70	100		dB
k <sub>SVR</sub>	Supply-voltage rejection ratio $(\Delta V_{CC}\pm/\Delta V_{IO})$	$V_{CC\pm} = \pm 9 \text{ V to } \pm$	15 V,	V <sub>O</sub> = 0	80	100		dB
los	Output short-circuit current				10	38	60	mA
Icc	Total supply curent	$V_{O} = 0$ ,	No load			8	16	mA
	Crosstalk attenuation (VO1/VO2)	V <sub>01</sub> = 10 V peak,	f = 1 kHz			110		dB

<sup>†</sup> All characteristics are measured under open-loop conditions, with zero common-mode input voltage, unless otherwise specified.



<sup>‡</sup> Full temperature ranges are: -40°C to 85°C for the SA5532 and SA5532A, and 0°C to 70°C for the NE5532 and NE5532A.

# NE5532, NE5532A, SA5532, SA5532A DUAL LOW-NOISE OPERATIONAL AMPLIFIERS

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# operating characteristics, $V_{CC\pm}$ = $\pm 15$ V, $T_A$ = $25^{\circ}C$

PARAMETER		TEST CONDITIONS	NE5532, SA5532			NE5532A, SA5532A				
		TEST CONDITIONS	MIN	TYP	MAX	MIN	TYP	MAX	UNIT	
SR	Slew rate at unity gain			9			9		V/μs	
	Overshoot factor	$V_I = 100 \text{ mV}, \qquad A_{VD} = 1, \\ R_L = 600 \ \Omega, \qquad C_L = 100 \text{ pF}$		10			10		%	
\ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \	Equivalent input noise voltage	f = 30 Hz		8			8	10	->//s/I-I=	
V <sub>n</sub>		f = 1 kHz		5			5	6	nV/√ <del>Hz</del>	
In	Facilitation desire accept	f = 30 Hz	2.7				2.7		- A / /I I=	
	Equivalent input noise current	f = 1 kHz		0.7 0.7			pA/√Hz			







#### **PACKAGING INFORMATION**

Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish	MSL Peak Temp <sup>(3)</sup>
NE5532AD	ACTIVE	SOIC	D	8	75	Pb-Free (RoHS)	CU NIPDAU	Level-2-250C-1 YEAR
NE5532ADR	ACTIVE	SOIC	D	8	2500	Pb-Free (RoHS)	CU NIPDAU	Level-2-250C-1 YEAR
NE5532AIP	OBSOLETE	PDIP	Р	8		None	Call TI	Call TI
NE5532AP	ACTIVE	PDIP	Р	8	50	Pb-Free (RoHS)	CU NIPDAU	Level-NC-NC-NC
NE5532APSR	ACTIVE	SO	PS	8	2000	Pb-Free (RoHS)	CU NIPDAU	Level-2-260C-1 YEAR/ Level-1-235C-UNLIM
NE5532D	ACTIVE	SOIC	D	8	75	Pb-Free (RoHS)	CU NIPDAU	Level-2-250C-1 YEAR
NE5532DR	ACTIVE	SOIC	D	8	2500	Pb-Free (RoHS)	CU NIPDAU	Level-2-250C-1 YEAR
NE5532IP	OBSOLETE	PDIP	Р	8		None	Call TI	Call TI
NE5532P	ACTIVE	PDIP	Р	8	50	Pb-Free (RoHS)	CU NIPDAU	Level-NC-NC-NC
NE5532PSR	ACTIVE	SO	PS	8	2000	Pb-Free (RoHS)	CU NIPDAU	Level-2-260C-1 YEAR/ Level-1-235C-UNLIM
SA5532AD	ACTIVE	SOIC	D	8	75	Pb-Free (RoHS)	CU NIPDAU	Level-2-260C-1 YEAR/ Level-1-235C-UNLIM
SA5532ADR	ACTIVE	SOIC	D	8	2500	Pb-Free (RoHS)	CU NIPDAU	Level-2-260C-1 YEAR/ Level-1-235C-UNLIM
SA5532AP	ACTIVE	PDIP	Р	8	50	Pb-Free (RoHS)	CU NIPDAU	Level-NC-NC-NC
SA5532D	ACTIVE	SOIC	D	8	75	Pb-Free (RoHS)	CU NIPDAU	Level-2-260C-1 YEAR/ Level-1-235C-UNLIM
SA5532DR	ACTIVE	SOIC	D	8	2500	Pb-Free (RoHS)	CU NIPDAU	Level-2-260C-1 YEAR/ Level-1-235C-UNLIM
SA5532P	ACTIVE	PDIP	Р	8	50	Pb-Free (RoHS)	CU NIPDAU	Level-NC-NC-NC

<sup>&</sup>lt;sup>(1)</sup> The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

None: Not yet available Lead (Pb-Free).

**Pb-Free** (**RoHS**): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Green (RoHS & no Sb/Br): TI defines "Green" to mean "Pb-Free" and in addition, uses package materials that do not contain halogens, including bromine (Br) or antimony (Sb) above 0.1% of total product weight.

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDECindustry standard classifications, and peak solder temperature.

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<sup>(2)</sup> Eco Plan - May not be currently available - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.



# **PACKAGE OPTION ADDENDUM**

18-Feb-2005

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#### P (R-PDIP-T8)

#### PLASTIC DUAL-IN-LINE



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- C. Falls within JEDEC MS-001

For the latest package information, go to http://www.ti.com/sc/docs/package/pkg\_info.htm

# D (R-PDSO-G8)

### PLASTIC SMALL-OUTLINE PACKAGE



NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
- D. Falls within JEDEC MS-012 variation AA.





NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



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